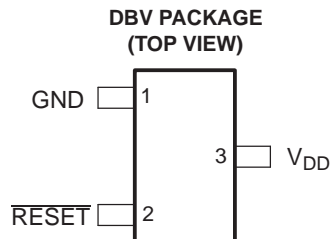


FEATURES

- **Controlled Baseline**
 - One Assembly Site
 - One Test Site
 - One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree ⁽¹⁾**
- **3-Pin SOT-23 Package**
- **Supply Current of 9 μ A (Typical)**
- **Precision Supply Voltage Monitor**
2.5 V, 3 V, 3.3 V, 5 V
- **Power-On Reset Generator With Fixed Delay Time of 200 ms**
- **Pin-for-Pin Compatible With MAX 809**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



DESCRIPTION

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

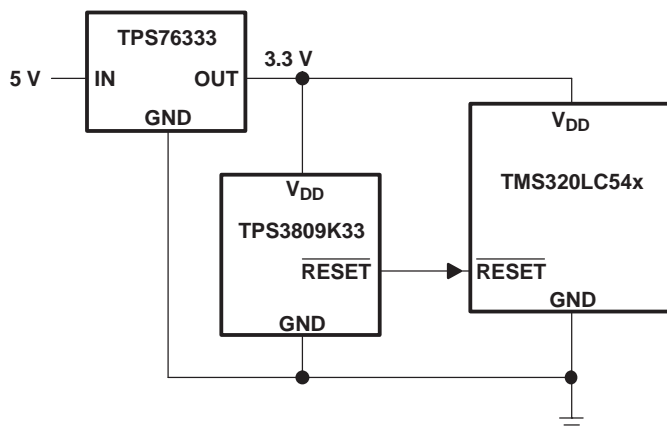
During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors V_{DD} and keeps $\overline{\text{RESET}}$ active as long as V_{DD} remains below the threshold voltage V_{IT} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_{\text{d(typ)}} = 200$ ms, starts after V_{DD} has risen above the V_{IT} . When the supply voltage drops below the V_{IT} , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed-sense V_{IT} set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23 package. The TPS3809 devices are characterized for operation over a temperature range of –55°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TYPICAL APPLICATIONS



- Applications Using DSPs, Microcontrollers, or Microprocessors
- Wireless Communication Systems
- Portable/Battery-Powered Equipment
- Programmable Controls
- Intelligent Instruments
- Industrial Equipment
- Notebook/Desktop Computers
- Automotive Systems

AVAILABLE OPTIONS

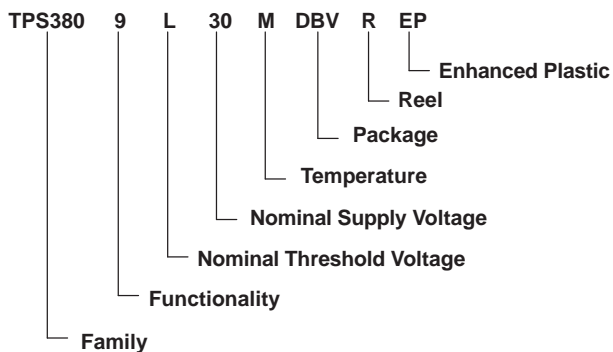
T _A	DEVICE NAME	THRESHOLD VOLTAGE	MARKING
–55°C to 125°C	TPS3809L30MDBVREP ⁽¹⁾	2.64 V	PLYM
	TPS3809K33MDBVREP ⁽¹⁾	2.93 V	PLZM
	TPS3809I50MDBVREP ⁽¹⁾	4.55 V	PMAM

(1) The DBVR passive indicates tape and reel of 3000 parts.

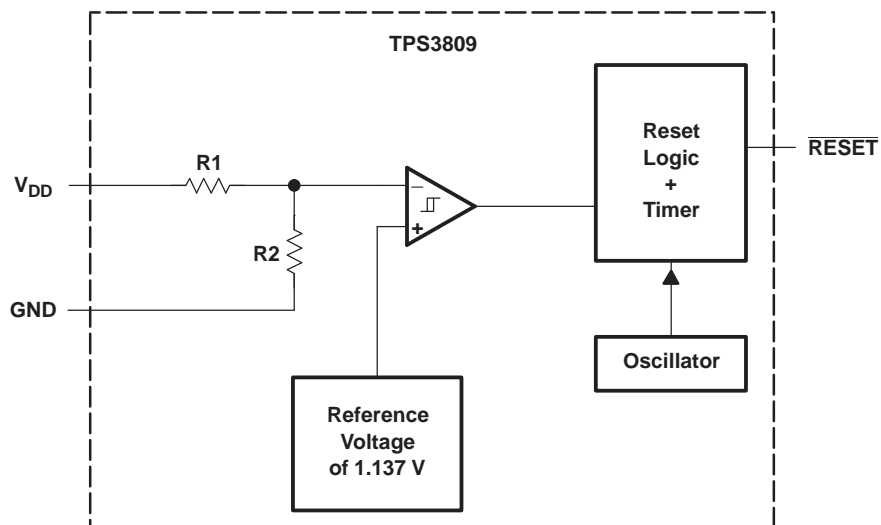
FUNCTION/TRUTH TABLE

V _{DD} > V _{IT}	RESET
0	L
1	H

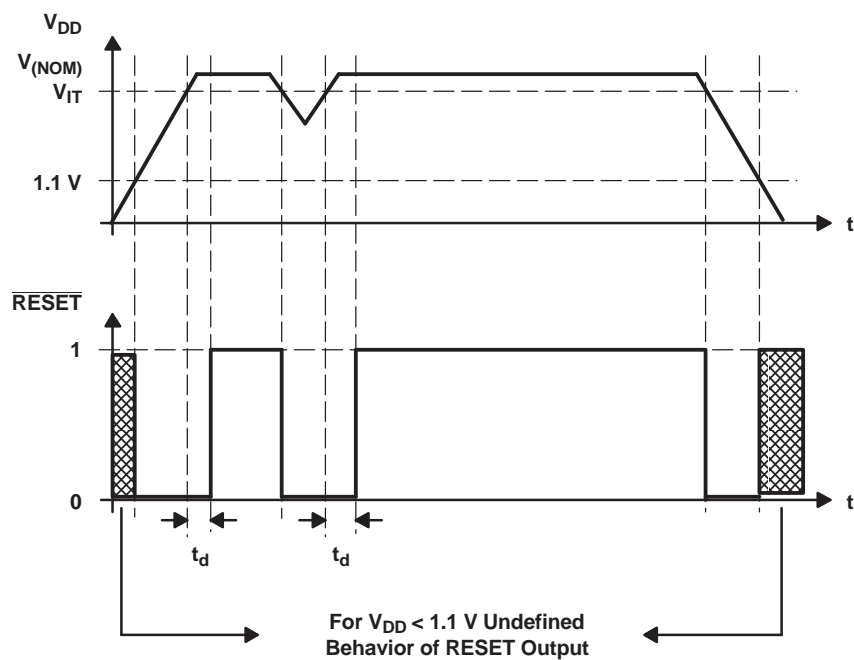
ORDERING INFORMATION



FUNCTIONAL BLOCK DIAGRAM



TIMING DIAGRAM



TPS3809L30-EP, TPS3809K33-EP, TPS3809I50-EP 3-PIN SUPPLY VOLTAGE SUPERVISORS

SGLS369A – AUGUST 2006 – REVISED NOVEMBER 2006

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage ⁽²⁾	V _{DD}		7	V
	All other pins	–0.3	7	
I _{OL}	Maximum low output current		5	mA
I _{OH}	Maximum high output current		–5	mA
I _{IK}	Input clamp current	V _I < 0 or V _I > V _{DD}	±20	mA
I _{OK}	Output clamp current	V _O < 0 or V _O > V _{DD}	±20	mA
Continuous total power dissipation		See Dissipation Rating Table		
T _A	Operating free-air temperature range	–55	125	°C
T _{stg}	Storage temperature range	–65	150	°C
Soldering temperature			260	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to GND. For reliable operation the device should not be operated at 7 V for more than t = 1000h continuously.

Dissipation Ratings

PACKAGE	T _A < 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

Recommended Operating Conditions

	MIN	MAX	UNIT
V _{DD} Supply voltage	2	6	V
T _A Operating free-air temperature	–55	125	°C

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{OH}	High-level output voltage	V _{DD} = 2.5 V to 6 V, I _{OH} = −500 μA	V _{DD} − 0.2			V
		V _{DD} = 3.3 V, I _{OH} = −2 mA	V _{DD} − 0.4			
		V _{DD} = 6 V, I _{OH} = −4 mA	V _{DD} − 0.4			
		V _{DD} = 6 V, I _{OH} = −4 mA, T _A = 125°C	V _{DD} − 0.5			
V _{OL}	Low-level output voltage	V _{DD} = 2 V to 6 V, I _{OL} = 500 μA	0.2			V
		V _{DD} = 3.3 V, I _{OL} = 2 mA	0.4			
		V _{DD} = 6 V, I _{OL} = 4 mA	0.4			
Power-up reset voltage ⁽¹⁾		V _{DD} ≥ 1.1 V, I _{OL} = 50 μA	0.2			V
V _{IT−}	Negative-going input threshold voltage ⁽²⁾	TPS3809L30	2.58	2.64	2.7	V
		TPS3809K33	2.87	2.93	2.99	
		TPS3809I50	4.45	4.55	4.65	
V _{hys}	Hysteresis	TPS3809L30	35			mV
		TPS3809K33	40			
		TPS3809I50	60			
I _{DD}	Supply current	V _{DD} = 2 V, Output unconnected	9	12		μA
		V _{DD} = 6 V, Output unconnected	20	25		
C _i	Input capacitance	V _I = 0 V to V _{DD}	5			pF

(1) The lowest supply voltage at which **RESET** becomes active. t_r, V_{DD} ≥ 15 µs/V.

(2) To ensure best stability of the threshold voltage, a bypass capacitor (0.1-µF ceramic) should be placed near the supply terminals.

Timing Requirements

R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t _w Pulse width at V _{DD}	V _{DD} = V _{IT–} + 0.2 V, V _{DD} = V _{IT–} – 0.2 V	3		µs

Switching Characteristics

R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _d	Delay time	V _{DD} ≥ V _{IT–} + 0.2 V, See timing diagram	120	200	280	ms
t _{PHL}	Propagation (delay) time, high- to low-level output	V _{DD} to RESET delay V _{IL} = V _{IT–} – 0.2 V, V _{IH} = V _{IT–} + 0.2 V		1		ms

TYPICAL CHARACTERISTICS

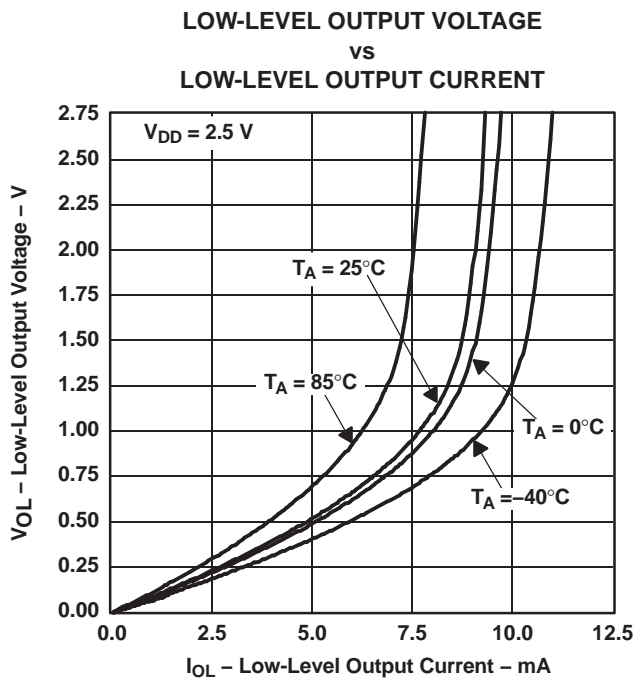


Figure 1.

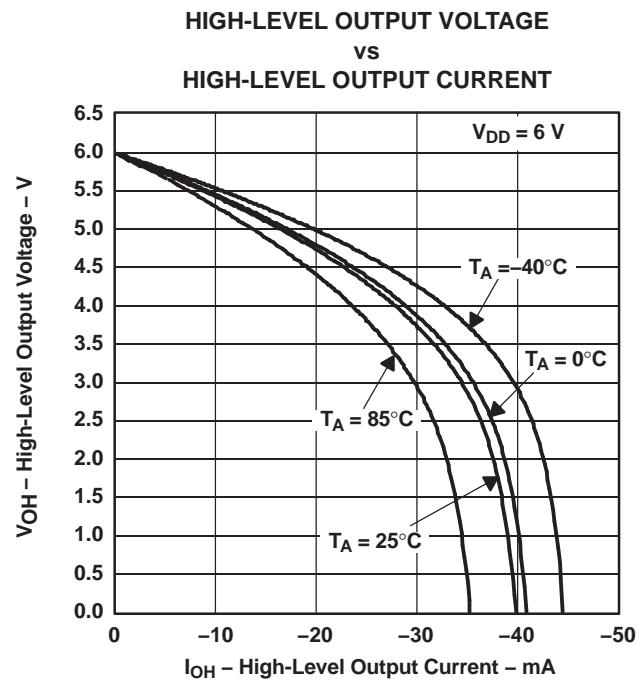


Figure 2.

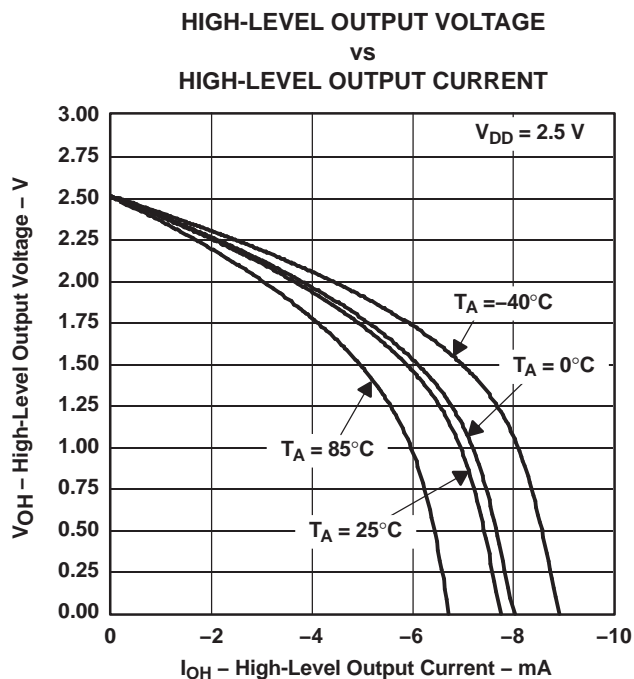


Figure 3.

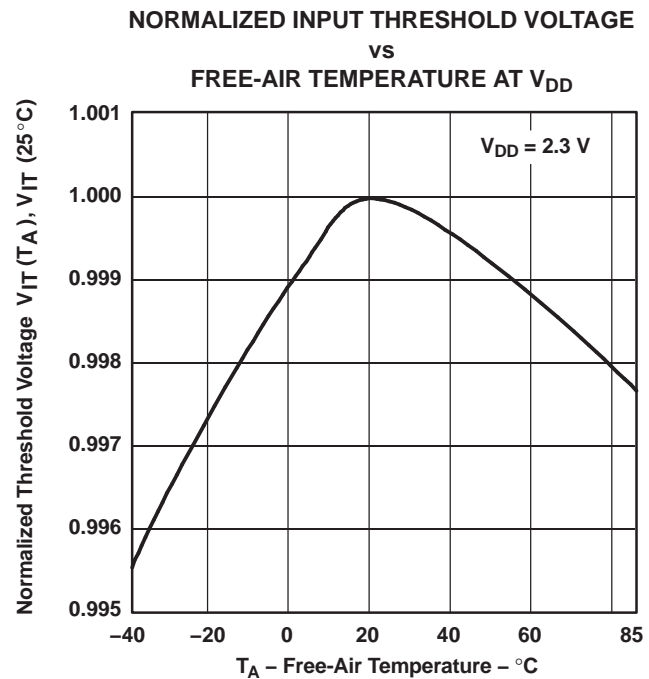


Figure 4.

TYPICAL CHARACTERISTICS (continued)

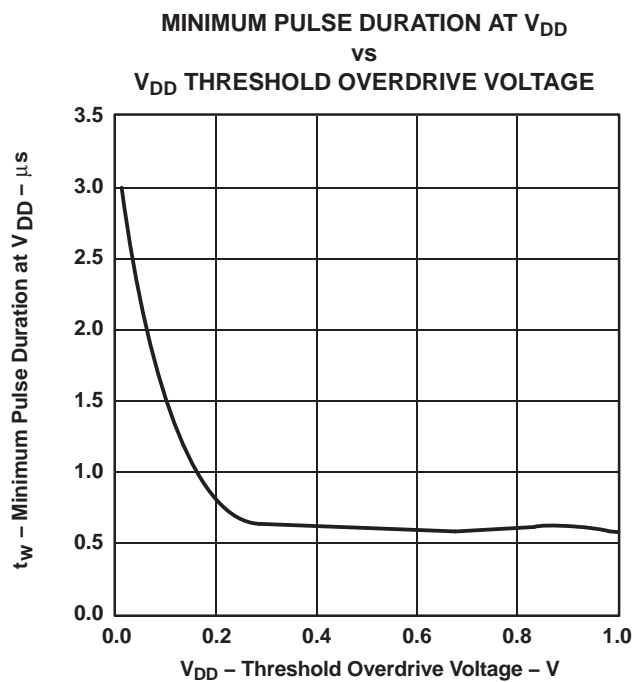


Figure 5.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TPS3809I50MDBVREP	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	PMAM	Samples
TPS3809K33MDBVREP	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	PLZM	Samples
TPS3809L30MDBVREP	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	PLYM	Samples
V62/06636-01XE	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	PLYM	Samples
V62/06636-02XE	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	PLZM	Samples
V62/06636-03XE	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	PMAM	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

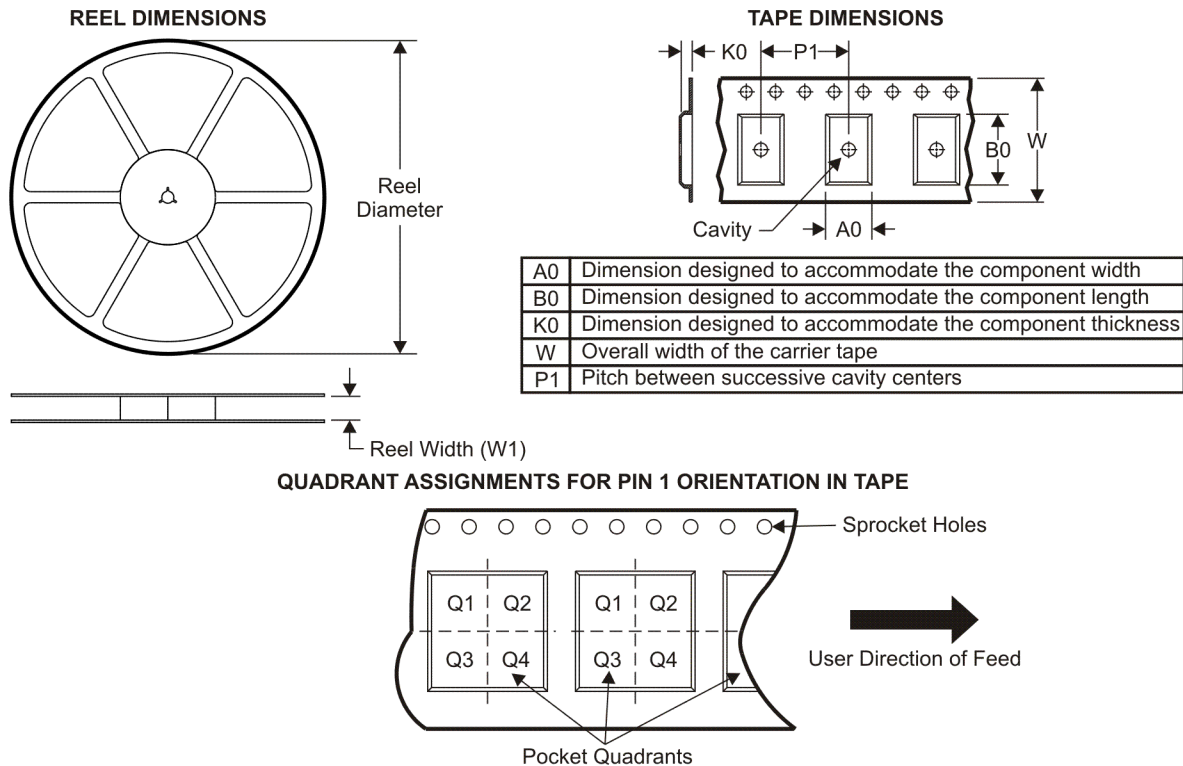
OTHER QUALIFIED VERSIONS OF TPS3809I50-EP, TPS3809K33-EP, TPS3809L30-EP :

- Catalog: [TPS3809I50](#), [TPS3809K33](#), [TPS3809L30](#)
- Automotive: [TPS3809I50-Q1](#), [TPS3809K33-Q1](#), [TPS3809L30-Q1](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3809I50MDBVREP	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33MDBVREP	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809L30MDBVREP	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

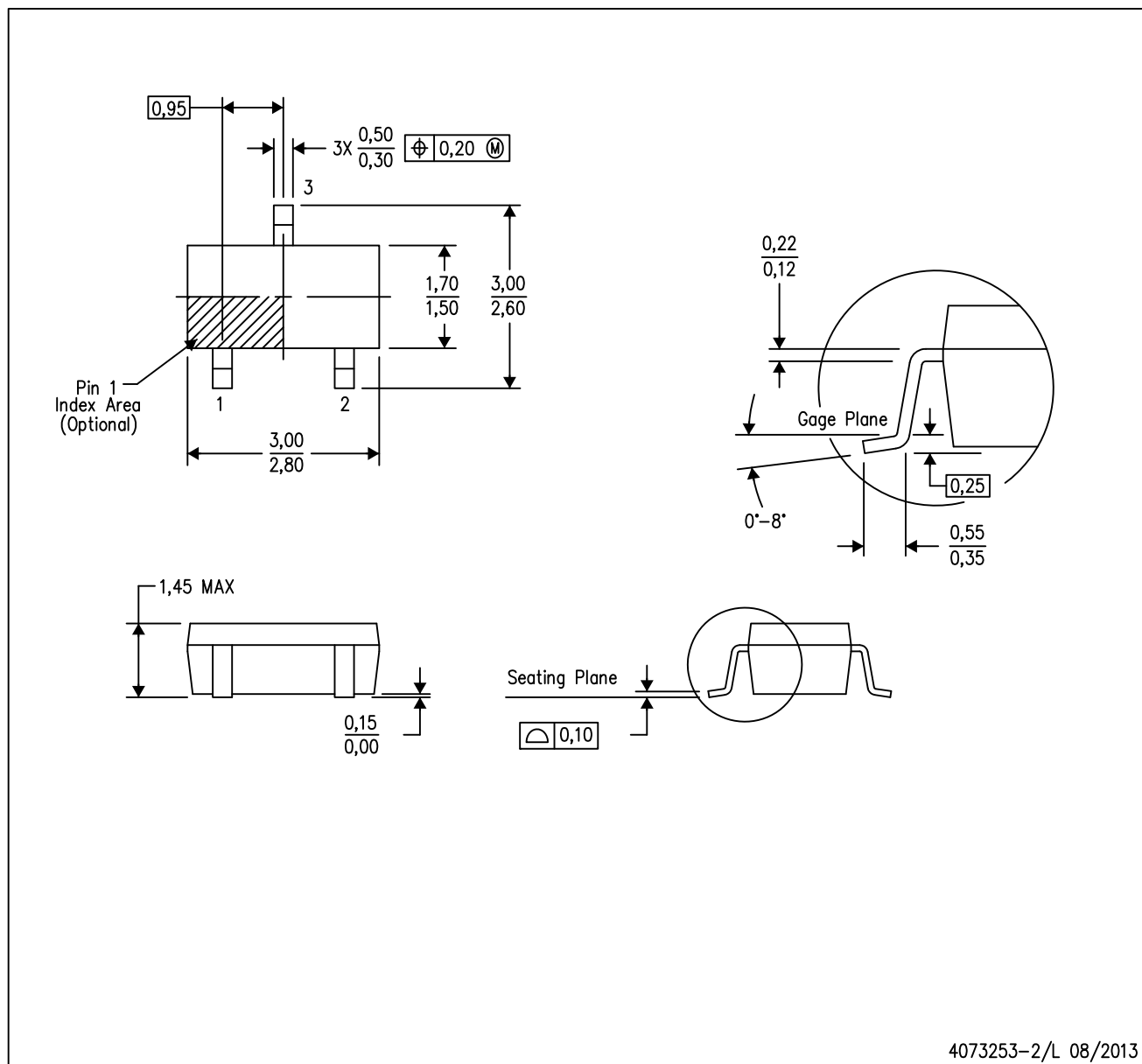


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3809I50MDBVREP	SOT-23	DBV	3	3000	182.0	182.0	20.0
TPS3809K33MDBVREP	SOT-23	DBV	3	3000	182.0	182.0	20.0
TPS3809L30MDBVREP	SOT-23	DBV	3	3000	182.0	182.0	20.0

DBV (R-PDSO-G3)

PLASTIC SMALL-OUTLINE PACKAGE

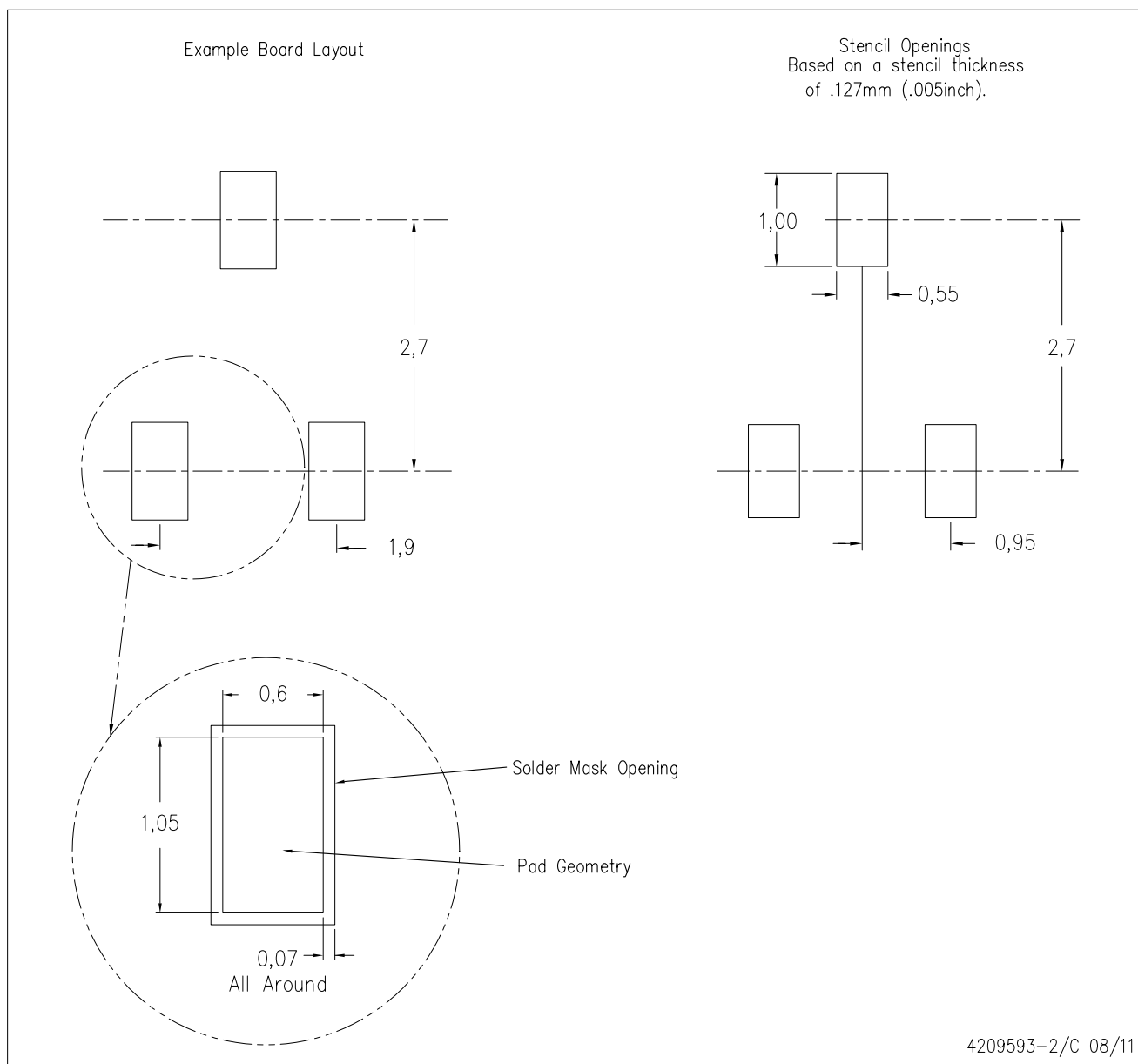


4073253-2/L 08/2013

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.

DBV (R-PDSO-G3)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com